

ABSTRACT

A method includes:

- A. providing a substrate having a first surface and a second surface, the first surface being adapted for mounting an electronic device thereon;
- B. forming a grid of electrically conductive vias extending from a region proximate the first surface to a region proximate the second surface, each via being one of a signal via, a ground via and a power via;
- C. removing at least one of the vias to form a void between at least one ground via and at least one power via; and
- D. connecting each of the at least one ground via proximate the void to one of the at least one power vias proximate the void with a filter device proximate the second surface of the substrate.